									406	62C-0	9A
S E	Ξ	R	V	I	С	Е		Ν	0	Т	Е
							SUPER	SEDE	S: 4062	2C-09	
4062C Semiconductor Process Control System 16320-66551 Pin Board											
Serial N	umber	rs: See	below.								
Solution for open relay coil failure											
Duplicate Service Notes:											
4062UX 4062C-0 4062F-0	09A Serial Numbers: 2830J00428/2830J00429										
To Be Performed By: Agilent-Qualified Personnel											
Parts R	equire	d:									
P/N		De	escription	1		Qua	ntity				
16320-6	6551	Pi	in Board			(See 1	note.)*				
*The quantities depend on the situation.											
										Continue	ed
							DATE:	Janua	ary 1999)	

ADMINISTRATIVE INFORMATION

SERVICE NOTE CLASSIFICATION: MODIFICATION RECOMMENDED								
ACTION CATEGORY:	 IMMEDIATELY ON SPECIFIED FAILURE AGREEABLE TIME 	STANDARDS: LABOR 0.5 Hours						
LOCATION CATEGORY:	 ☐ CUSTOMER INSTALLABLE ■ ON-SITE ☐ SERVICE CENTER 	SERVICE □ RETURN USED □ RETURN INVENTORY: □ SCRAP PARTS: ■ SCRAP □ SEE TEXT □ SEE TEXT						
AVAILABILITY:	PRODUCT'S SUPPORT LIFE	AGILENT RESPONSIBLE UNTIL: January 2001						
AUTHOR: MO	ENTITY: 3300	ADDITIONAL INFORMATION:						

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Situation:

The relay test of the switching matrix fails with the following conditions:

• The relay test indicates a normally open relay will not close.

--or--

- The relay test indicates a normally closed relay will not open.
- The relay test failure is consistent (not intermittent).

The resistance of the suspected relay's coil is over one mega ohm. (Measure the coil resistance on the reverse side of the board by using a hand-held multimeter.) The resistance of a good relay coil is approximately 1.2 kohm (2-line relay) or 800 ohm (3-line relay).

Solution / Action:

Replace the pin board indicated by the relay test with a pin board whose date stamp is 980506 (May 6, 1998) or later.

The failure is caused by the breaking of a relay coil. The breaking usually occurs if water penetrates the filler of the relay and reaches the coil wire, or if corrosive material exists on the surface of the wire. These problems have been corrected by changing the manufacturing processes.